

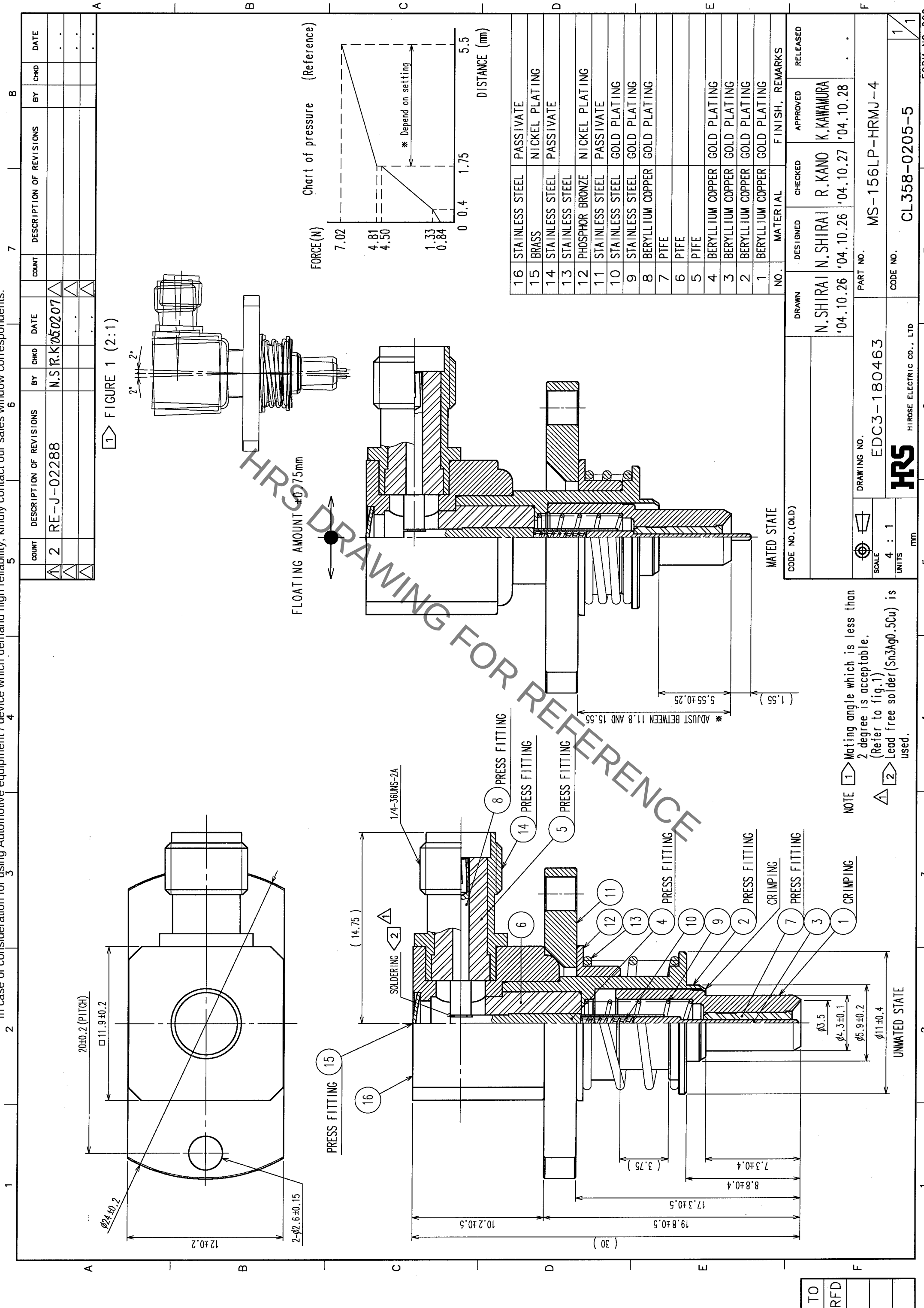
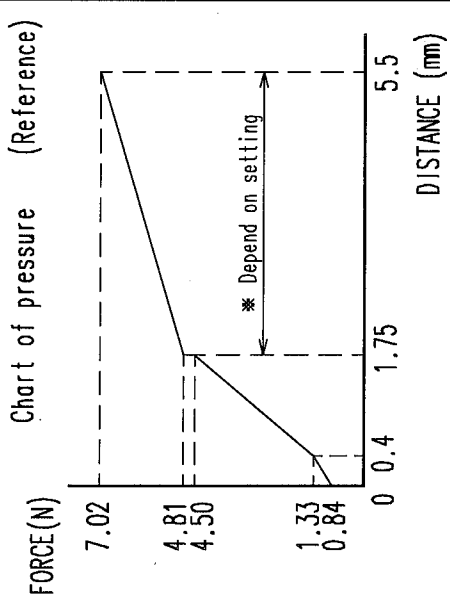


FIGURE 1 (2:1)



16	STAINLESS STEEL	PASSIVATE
15	BRASS	NICKEL PLATING
14	STAINLESS STEEL	PASSIVATE
13	STAINLESS STEEL	PASSIVATE
12	PHOSPHOR BRONZE	NICKEL PLATING
11	STAINLESS STEEL	PASSIVATE
10	STAINLESS STEEL	GOLD PLATING
9	STAINLESS STEEL	GOLD PLATING
8	BERYLLIUM COPPER	GOLD PLATING
7	PTFE	
6	PTFE	
5	PTFE	
4	BERYLLIUM COPPER	GOLD PLATING
3	BERYLLIUM COPPER	GOLD PLATING
2	BERYLLIUM COPPER	GOLD PLATING
1	BERYLLIUM COPPER	GOLD PLATING
NO.	MATERIAL	FINISH, REMARKS

DRAWING NO. EDC3-180463		PART NO. MS-156LP-HRMJ-4	
SCALE 4 : 1		CODE NO. CL358-0205-5	
UNITS mm		FORM NO. 229	
DRAWN N. SHIRAI		CHECKED R. KANO	
DESIGNED N. SHIRAI		APPROVED K. KAWAMURA	
DATE '04.10.26		DATE '04.10.27	
COUNT		RELEASED	

NOTE 1 Mating angle which is less than 2 degree is acceptable. (Refer to fig.1)
2 Lead free solder (Sn3Ag0.5Cu) is used.